Minutes of WP-meeting 239

Attendance:
DESY: Ties Behnke, Ralf Diener, Ulrich Einhaus, Leif Jönsson, Claus Kleinwort, Paul Malek, Oliver Schäfer, Sebastian, Laura
Fuzebox: Alain Bellerieve, Jochen Kaminski, Michael Lupberger, Amir Shirazi, Ron Settles, Jan Timmermans

General News:
Ralf announced that the final version of the GEM-paper is ready and asked everyone to check again the author list. In particular people who have worked on the project but have left the respective institute should be listed with both affiliations, the one where the work was done and the new one with '*now at*'. Another question was the procedure of submitting the paper to a journal and to arXiv. Jan mentioned, that it would be less work to submit to arXiv only after having an accepted version by the journal, because no new version had to be uploaded. Leif pointed out that on the other hand the paper would be faster available for other to read if submitted immediately to arXiv. A slight tendency for the second approach was felt, in particular since a fast submission is preferential for the PhD process of Felix. Finally, also the target journal of LCTPC papers was discussed and a wide preference for NIM was voiced.
Since DESY has an open access policy, it will pay to make the paper openly available.

PCMAG/LP setup, test beam:
Ralf: PCMAG/TRACI/test beam area:

- Today PCMAG is cooled down and test excitations are panned for today or tomorrow. Oliver has cleaned the counting hut and rearranged components.

News from the groups:
Jochen reported that the Bonn group has installed the latest version of ILCsoft, Marlin and MarlinTPC. The new Marlin requires DD4HEP and DD4HEP requires Geant4. The installation process became even more challenging. If someone finds a way of easier installation, please report in an WPmtg.

Leif reported on the status of the chip carrier. The new system based on an adaptor board and the CERN readout card is in operation. Leif showed pictures of the various components. At the beginning everything worked fine except one data line. It was assumed that this line had a bad solder connection. It was tried to improve the connection by applying some pressure. Unfortunately, several other lines lost connection during this effort. Therefore, the board was sent back to the company for resoldering (putting again in the reflow oven). During the AIDA meeting Leif heard that this problem has happened to others, too and that a lead alloy as soldering material would greatly improve the reliability of the connections.

AOB:
The next workpackage meeting will take place on March 31st.